

**REMARKS**

Acknowledgment of Applicants' claim to priority and receipt of the priority document in the parent application is respectfully requested.

The inadvertent omission of the word "to" in claim 1 has been remedied by the foregoing amendments. Accordingly, the rejection of the claims under 35 USC §112, second paragraph, can now be withdrawn.

Claims 1-3 were rejected under 35 USC §103 over CN '260. This rejection is respectfully traversed.

The present invention provides a lead-free solder in consisting essentially of at least one of 0.01-0.2% by weight of Mn and/or the same amount of Cr, at least one of 0.5-9% Ag and/or 0.5-5% Sb and at least 90.5% of tin. As shown in the table of page 13 of the application, the solders have a soldering temperature of 350°C or less.

In contrast, the Chinese reference relates to a braze made by melting a mixture of tin, silver, copper and CuCr13 at 400-500°C, forming ingots, and remelting the ingots in the same temperature range. That is clearly not a solder, and particularly not a solder having a soldering temperature of 350°C or less. Moreover, the Chinese reference contains copper and there is no teaching or suggestion of eliminating the copper from that composition. It is respectfully submitted that any of these facts considered alone is sufficient to obviate the rejection, and in combination, are clearly sufficient.

Claims 1-4 were rejection under 35 USC §103 over Tanaka '242. This reference relates to a tin-base white metal bearing alloy which is clearly not a solder, and especially not a solder having a soldering temperature at 350°C or less. That fact alone is respectfully submitted to eliminate this reference as a proper basis for a rejection under

Section 103. In addition, the invention in this reference is predicated on the presence of a nickel and there is no teaching or a suggestion of any composition which contains 2% nickel or less for any purpose. Withdrawal of the rejection based on Tanaka is respectfully requested.


Claims 5 and 6 were rejected under 35 USC §103 over Tanaka '242 in view of Tanaka '236. This rejection is respectfully traversed.

Tanaka '242 has been discussed above. Tanaka '236 is cited to allegedly show a backing plate which can be plated with copper in the same field of endeavor or analogous metallurgical art. However, even ignoring the fact that Tanaka '236 is not concerned with a solder but instead refers to a bearing material, the reference is predicated on the use of a lead containing alloy. No basis or motivated for combining the two Tanaka patents as therefore present, especially since Tanaka '242 relates to a composition which does not contain lead.

In light of the foregoing considerations, it is respectfully submitted that this application is in condition to be allowed and the early issuance of a notice of allowance is respectfully solicited.

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Respectfully submitted,

By 

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